Aloha,

Honolulu Community College is once again pleased to offer the 2021 Summer Engineering Academy (SEA). Space will be limited to 40 students, so please apply as soon as possible. The program will run from June 7, 2021 through July 16, 2021 from 8:00 AM - 12:00 PM, Monday through Friday. Note: classes will not be held on Friday, June 11, 2021 and Monday, July 5, 2021. The application deadline is Friday, June 4, 2021.

About SEA
SEA is an intensive six-week summer program that offers high school students the opportunity to learn, think and solve problems like an engineer. Students will apply their knowledge of math and science to practical projects, which will allow them to see concepts they have learned in the classroom come alive. Through lab work, group projects, lectures and assignments, students will explore the engineering fields related to transportation, science, computer, electrical and mechanical engineering. Students will meet other students with similar interests, collaborate on testing theories and find solutions to engineering problems.

As students complete SEA projects on materials, structures, chemical processes, circuit design, computer programming, robotics and other topics, they will gain insights into which engineering fields best match their abilities and interests. Students will rotate though different modules lasting for approximately two weeks each.

Students will also be provided with college success tools to help prepare them for entry into college. Students will be exposed to a college environment, identify general campus resources, demonstrate knowledge of college procedures, discuss the definition of success, and evaluate their academic and life goals. Students will attend this course once a week on Wednesdays from 8:00 to 9:00 am. Parents will attend a financial aid workshop and receive scholarship information. Date to be announced.

Prerequisites
Students are expected to have completed geometry and have basic computer skills. Students should also have completed high school level physics, chemistry or biology.

Questions
If you have any questions regarding the SEA program please call or email:
Norman Takeya
(808) 844-2376
ntakeya@hawaii.edu
Dear Summer Engineering Academy Applicant:

This checklist is provided to outline all the appropriate forms required to process your application.

WHAT: 2021 Summer Engineering Academy

WHEN: June 7, 2021 – July 16, 2021 (holidays 6/11 & 7/5); 8:00AM – 12:00PM

WHERE: Honolulu Community College, Building 2, 6th Floor

DEADLINE: Mail or hand deliver forms with registration fee by June 4, 2021. Applicants are encouraged to apply as soon as possible. Space is extremely limited this year.

REGISTRATION FEE: $250 (Please make checks payable Honolulu Community College) *A limited number of scholarships are available for those who qualify

MAIL TO: Honolulu Community College
PCATT – ATTN: Summer Engineering Academy
874 Dillingham Blvd.
Honolulu, HI 96817

OR HAND DELIVER: Honolulu Community College
Building 2, Room 507
PCATT – ATTN: Summer Engineering Academy
874 Dillingham Blvd.
Honolulu, HI 96817

REQUIRED FORMS: All forms must be completed and submitted with application
- Authorization for Student Participation Form
- Code of Conduct and Application
- Medical Consent Form
- UH Risk and Release Form
- Photo and Video Release Form

QUESTIONS: Contact Norman Takeya via Email – ntakeya@hawaii.edu
Permission is requested for your child to participate in: 2021 Summer Engineering Academy
Location: Honolulu Community College, 874 Dillingham Blvd., Building 2
Times and Dates: 8:00am - 12:00pm, Monday - Friday; June 7 - July 16, 2021 (Holidays 6/11 & 7/5)

Parent/Legal Guardian Permission:

Name of Participant: __________________________________________________________________

Participant Phone Number: _____________________________ (___ home ___ work ___ cell)

Participant E-mail Address: _____________________________________________________________

Emergency Contact: ___________________________________________________________________

Relationship to Student: ________________________________________________________________

Phone Number(s): _____________________________________________________________________

________ (initial) My child has my permission to attend the 2021 Summer Engineering Academy.

Transportation:

Participants are responsible for their own transportation to and from the event each day. Classes finish
daily at 12:00 PM. Your child will need to immediately be picked up from Honolulu Community College
after the completion of class. By checking the box below, you authorize your child to exit Honolulu
Community College to catch The Bus, public transportation and/or to carpool.

________ (initial) My child has my permission to leave the 2021 Summer Engineering Academy each
day to catch The Bus, public transportation and/or to carpool.

__________________________________________________________
Print Parent’s/Legal Guardian’s Name

__________________________________________________________
Parent’s/Legal Guardian’s Signature                      Date
2021 Summer Engineering Academy
Code of Conduct

Good conduct is expected of all participants in the Summer Engineering Academy. The following rules will apply to all participants. All participants should read and understand each item before completing the application and again before classes begin.

1. I will behave in a professional manner at all times as it reflects positively on myself and my school.
2. I will respect the rights of others including belongings, personal space and privacy.
3. I will keep my instructor/advisor informed of my whereabouts at all times. During the scheduled classes and events, I will not leave the Honolulu Community College campus without informing and obtaining approval from my instructor/advisor.
4. I will be properly attired for all class sessions and activities, including appropriate footwear.
5. I will attend and be on time for all sessions and participate in all activities.
6. I will respect all public and private property, including event facilities, at all times.
7. I will not use tobacco, alcohol or illegal drugs at any time. I understand that violations are subject to disciplinary action and legal consequences.
8. I will only take medication prescribed by a licensed physician. If I am required to take medication, I will have a copy of the prescription with me at all times.
9. I will report any accidents, injuries, illnesses or incidents to my instructor/advisor immediately.
10. I will not use inappropriate or profane language.
11. I will leave my valuables at home including excess money.
12. I will stay home if I am not feeling well or have been in close contact with someone who has been diagnosed with COVID-19.
13. I will notify my instructor/advisor immediately if I have a fever or am feeling ill.
14. I will practice physical distancing by maintaining a six feet distance between myself and others.
15. I will wear a mask at all times while on campus. Acceptable masks are at least two-ply, fits snugly on the face and covers both the nose and mouth.
16. While not required, students are highly encouraged to be fully vaccinated for COVID-19 before June 7, 2021.
17. My conduct shall be exemplary at all times. If I disregard the rules, I will be subject to disciplinary action and sent home immediately. My parent or guardian will be responsible for picking me up.
Application Questions:

1. Are you able to fully commit to attend the 2021 Summer Engineering Academy, every day from start to finish, 8:00 AM to 12:00 PM (noon), Monday through Friday, June 7, 2021 – July 16, 2021 (no classes will be held on Friday, June 11 and Monday, July 5)?

☐ Yes       ☐ No

2. Indicate the grade level you will be starting in the Fall 2021 (July/August 2021): ____________

3. What school will you be attending in the Fall 2021: ________________________________

4. In five (5) sentences or less, tell us why you want to attend the Summer Engineering Academy?

5. What technologies do you have experience with?

6. If you are unable to pay the $250 fee, please explain the circumstances to granting a scholarship (e.g., free or reduced lunch eligible). Supporting documentation may be required.

I have read the Code of Conduct for the 2021 Summer Engineering Academy and agree to abide by these rules. I certify the responses in my application are true to the best of my knowledge.

Print Name of Student       Student Signature       Date

Print Name of Parent/Guardian       Parent/Guardian Signature       Date
UNIVERSITY OF HAWAI‘I
HONOLULU COMMUNITY COLLEGE

Name of Participant (Last Name, First Name, Middle Initial): _________________________________________

Program: 2021 Summer Engineering Academy      Date of Program:       June 7, 2021 – July 16, 2021

ASSUMPTION OF RISK AND RELEASE

I/We, the undersigned, certify that the above-named child is in good physical health and is able to participate in all activities of the above-named program.

I/We also understand and acknowledge that there are inherent dangers and risks involved with participation in the above-named program with the University of Hawaiʻi, which include, but are not limited to: working with electronic devices, networking devices and computers.

I/We understand that I/We should be covered during the Dates of Program above by a private medical and liability policy; and I/We further understand that the University of Hawaiʻi does not provide such insurance or otherwise indemnify individuals with respect to injuries or other liabilities arising out of participation in the above-named program.

Therefore, in consideration of the above-named child being permitted to participate in the above-named program, I/We hereby agree to assume all risks and responsibilities surrounding his/her participation in the above-named program. I/We have read and understand any and all written materials setting forth the requirements for participation in the above referenced activity, as well as those explained by the instructor(s), and I/We agree to strictly observe them. Further, I/We do for myself, my heirs, executors, and administrators hereby accept full responsibility for my child’s participation and agree to indemnify, release and discharge the University of Hawaiʻi, State of Hawaiʻi, its officers, employees, agents, and assigns from any and all claims or actions for property damage, personal injury, and/or death arising from such participation in the above named program or growing out of or caused by any acts or omissions of the above named child during their participation in above named program.

________________________________________________                       _____________________
Signature of Parent(s)/Guardian(s)         Date

________________________________________________
Printed Name(s)_
UNIVERSITY OF HAWAI‘I
HONOLULU COMMUNITY COLLEGE

Name of Participant (Last Name, First Name, Middle Initial): ________________________________________

Program:  2021 Summer Engineering Academy   Date of Program:   June 7, 2021 – July 16, 2021

MEDICAL CONSENT FORM

I/We, the undersigned, consent to and authorize any medical professional and others working under their supervision to treat the above-named child for any injury or illness arising from or related to their participation in the above-named program.

I/We further agree to pay any and all medical expenses, costs and other charges and to release and discharge and hold harmless the University of Hawai‘i, State of Hawai‘i, its officers, employees, agents, and assigns from and against any liability or any claims or demands arising from or connected with such medical treatment or care.

IN CASE OF EMERGENCY:

First Person to Contact: ______________________________________ Phone: _____________________

Second Person to Contact: ______________________________________ Phone: _____________________

Physician to Contact: ______________________________________ Phone: _____________________

MEDICAL INSURANCE COVERAGE:

☐ My child has medical coverage with (plan name): ________________________________

☐ My child is NOT covered by any medical insurance.

Does your child have any allergies or medical conditions we need to be aware of? Explain below

_______________________________________________________________________________________

_______________________________________________________________________________________

__________________________________________________                ___________________________
Signature of Parent(s)/Guardian(s)                                       Date

__________________________________________________
Print Name(s)
Photo and Video Release Form

I understand the photograph(s) or video, or audio recording(s) taken of me on behalf of my participation in the Summer Engineering Academy at Honolulu Community College (hereinafter called “the College”) may be used in connection with publicizing the College, its activities and academic programs to the general public.

I hereby irrevocably authorize the College to copy, exhibit, publish or distribute any and all such images and audio of me or wherein I appear, including composite or artistic forms and media, for purposes of publicizing the College’s programs or for any other lawful purpose. These images may be used in printed publications, multimedia presentations or on websites. I agree that I will make no monetary or other claim against the College for the use of the interview and/or photograph(s)/video.

In addition, I waive any right to inspect or approve the finished product, including written copy, wherein my likeness appears.

I hereby hold harmless and release the College from all claims, demands and causes of action which I, my heirs, representatives, executors, administrators, or any other persons acting on my behalf or on behalf of my estate have or may have by reason of this authorization.

Participant:

I have read the above description and give my consent for the use as indicated above.

Printed Name: ___________________________________________
Signature: _______________________________________________   Date: ____________________
Email: __________________________________________________
Address: _________________________________________________
City, State, Zip: _____________________________________________
Telephone: ________________________________________________

If the person signing is under age 18, there should be consent by a parent or guardian, as follows:
I hereby certify that I am the parent or guardian of ______________________, the minor named above, and do hereby give my consent without reservations to the foregoing on behalf of this person.

Parental/Guardian Permissions (if applicable):

Printed Name: ___________________________________________
Signature: _______________________________________________   Date: ____________________
Phone Number: ___________________________________________